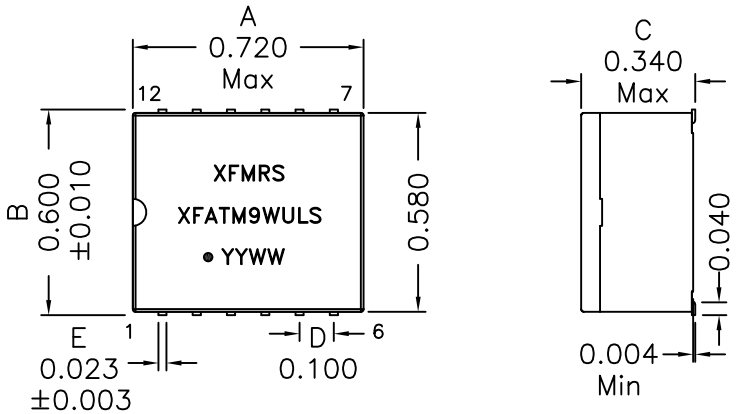
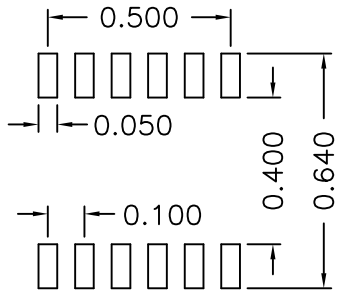
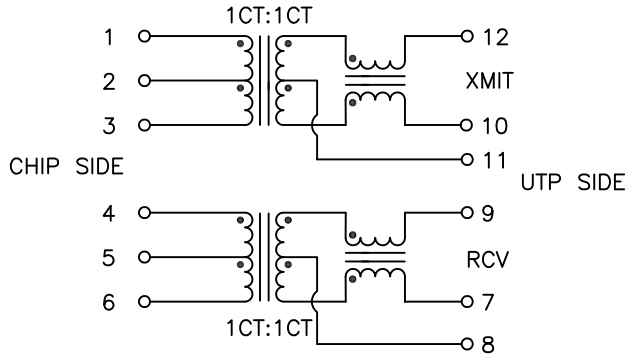
1. Dimensions:





SUGGESTED PAD LAYOUT

2. Schematic:



3. Electrical Specifications: @25°C

UTP Impedance: 100 OHMS

Turns Ratio: TX=1CT:1CT±2% RX=1CT:1CT±2%

Isolation Voltage: 2500Vrms, Input to Output

UTP Side OCL: 350uH Min @100KHz 0.1V, 8mAdc

UTP Side Q: 16 Min @100KHz 0.1V,

Rise Time (10−90%): 4.0ns Typical

Insertion Loss (1−100MHz): −1.0dB Maximum

Return Loss: 30MHz 60MHz 80MHz
−20dB −14dB −11.5dB Typ

CMRR: 30MHz 50MHz 100MHz
−42dB −37dB −33dB Typ

Crosstalk: 30MHz 60MHz 100MHz
−45dB −40dB −35dB Typ

Notes:

1. Solderability: Leads shall meet MIL−STD−202G, Method 208H for solderability.
2. Flammability: UL94V−0
3. ASTM oxygen index: > 28%
4. Insulation System: Class F 155°C. UL file E151556
5. Operating Temperature Range: All listed parameters are to be within tolerance from −40°C to +85°C
6. Storage Temperature Range: −55°C to +125°C
7. Aqueous wash compatible
8. SMD Lead Coplanarity: ±0.004"(0.102mm)
9. Electrical and mechanical specifications 100% tested
10. RoHS Compliant Component
11. Designed to meet UL60950 with supplementary insulation with an operating voltage up to 250Vrms.

DOC REV B/1

XFMRS Inc www.XFMRS.com	Title: 10/100 Ethernet		
UNLESS OTHERWISE SPECIFIED TOLERANCES: .xxx ±0.010 Dimensions in Inch	P/N: XFATM9WULS		REV. B
	DWN.	Yuan	Aug−05−13
	CHK.	YK Liao	Aug−05−13
SCALE 3:1 SHT 1 OF 1	APP.	BSJ	Aug−05−13

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